Amendment to the Claims

This listing of claims replaces all prior versions, and listings, of claims in the application.

Listing of claims:

- 1. (Currently amended) An adhesive composition comprising a bisphenol type epoxy(meth)acrylate (A), a di(meth)acrylate compound (B) having a cyclic ether structure, and a photopolymerization initiator (C), a (meth)acrylate phosphate compound (D), and a urethane (meth)acrylate (E).
- 2. (Cancelled)
- 3. (Cancelled)
- 4. (Cancelled)
- 5. (Cancelled)
- 6. (Original) The adhesive composition according to Claim
- 1, wherein the di(meth)acrylate compound (B) having a cyclic ether structure is a hydroxy-substituted (C4 to C10) tertiary aldehyde modified trimethylolpropane di(meth)acrylate or a modified product thereof.

7. (Original) The adhesive composition according to Claim 6, wherein the di(meth)acrylate compound (B) having a cyclic ether structure is a hydroxypivalic aldehyde modified trimethylolpropane di(meth)acrylate.

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- 8. (Currently amended) A bonded optical disk, wherein two optical disk substrates are adhered with a cured product of an adhesive composition according to anyone of Claims 1, 6 or to 7.
- 9. (Original) The bonded optical disk according to Claim 8, wherein at least one of the optical disk substrates is an optical disk substrate having a total reflection film or a translucent reflection film comprising silver or a silveralloy.